



Integrated
Circuit
Systems, Inc.

PRELIMINARY

ICS8535BI-01

Low SKEW, 1-TO-4
LVCMOS/LVTTL-TO-3.3V LVPECL FANOUT BUFFER

GENERAL DESCRIPTION



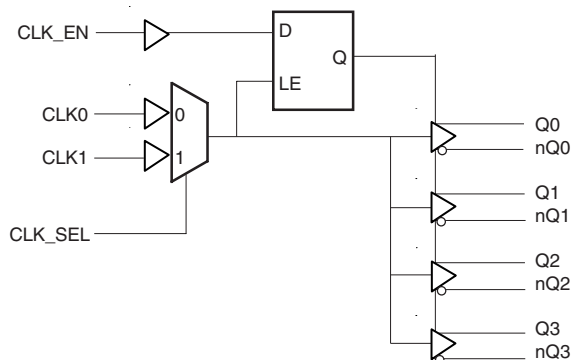
The ICS8535BI-01 is a low skew, high performance 1-to-4 LVCMOS/LVTTL-to-3.3V LVPECL fanout buffer and a member of the HiPerClockS™ family of High Performance Clock Solutions from ICS. The ICS8535BI-01 has two single ended clock inputs. the single ended clock input accepts LVCMOS or LVTTL input levels and translate them to 3.3V LVPECL levels. The clock enable is internally synchronized to eliminate runt clock pulses on the output during asynchronous assertion/deassertion of the clock enable pin.

Guaranteed output and part-to-part skew characteristics make the ICS8535BI-01 ideal for those applications demanding well defined performance and repeatability.

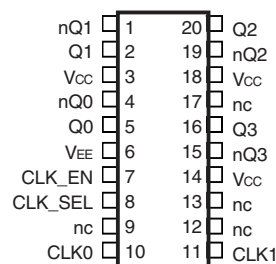
FEATURES

- 4 differential 3.3V LVPECL outputs
- Selectable CLK0 or CLK1 inputs for redundant and multiple frequency fanout applications
- CLK0 or CLK1 can accept the following input levels: LVCMOS or LVTTL
- Maximum output frequency: 266MHz
- Translates LVCMOS and LVTTL levels to 3.3V LVPECL levels
- Output skew: TBD
- Part-to-part skew: TBD
- Propagation delay: 1.3ns (typical)
- Additive phase jitter, RMS: 0.04ps (typical)
- 3.3V operating supply
- Lead-Free package RoHS compliant
- -40°C to 85°C ambient operating temperature

BLOCK DIAGRAM



PIN ASSIGNMENT

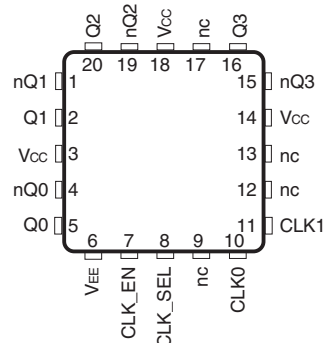


ICS8535BI-01 20-Lead TSSOP

4.4mm x 6.5mm x 0.92mm body package

G Package

Top View



20-Lead VFQFN

4mm x 4mm x 0.95 package body

K Package

Top View

The Preliminary Information presented herein represents a product in prototyping or pre-production. The noted characteristics are based on initial product characterization. Integrated Circuit Systems, Incorporated (ICS) reserves the right to change any circuitry or specifications without notice.



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TABLE 1. PIN DESCRIPTIONS

Number	Name	Type		Description
1, 2	nQ1, Q1	Output		Differential output pair. LVPECL interface levels.
3, 14, 18	V _{CC}	Power		Positive supply pins.
4, 5	nQ0, Q0	Output		Differential output pair. LVPECL interface levels.
6	V _{EE}	Power		Negative supply pin.
7	CLK_EN	Input	Pullup	Synchronizing clock enable. When HIGH, clock outputs follow clock input. When LOW, Q outputs are forced low, nQ outputs are forced high. LVC MOS / LVTTL interface levels.
8	CLK_SEL	Input	Pulldown	Clock select input. When HIGH, selects CLK1 input. When LOW, selects CLK0 input. LVC MOS / LVTTL interface levels.
9, 12, 13, 17	nc	Unused		No connect.
10	CLK0	Input	Pulldown	LVC MOS / LVTTL clock input.
11	CLK1	Input	Pulldown	LVC MOS / LVTTL clock input.
15, 16	nQ3, Q3	Output		Differential output pair. LVPECL interface levels.
19, 20	nQ2, Q2	Output		Differential output pair. LVPECL interface levels.

NOTE: *Pullup* and *Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

TABLE 2. PIN CHARACTERISTICS

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C _{IN}	Input Capacitance			4		pF
R _{PULLUP}	Input Pullup Resistor			51		KΩ
R _{PULLDOWN}	Input Pulldown Resistor			51		KΩ



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TABLE 3A. CONTROL INPUT FUNCTION TABLE

Inputs			Outputs	
CLK_EN	CLK_SEL	Selected Source	Q0:Q3	nQ0:nQ3
0	0	CLK0	Disabled; LOW	Disabled; HIGH
0	1	CLK1	Disabled; LOW	Disabled; HIGH
1	0	CLK0	Enabled	Enabled
1	1	CLK1	Enabled	Enabled

After CLK_EN switches, the clock outputs are disabled or enabled following a rising and falling input clock edge as show in Figure 1.

In the active mode, the state of the outputs are a function of the CLK0 and CLK1 inputs as described in Table 3B.

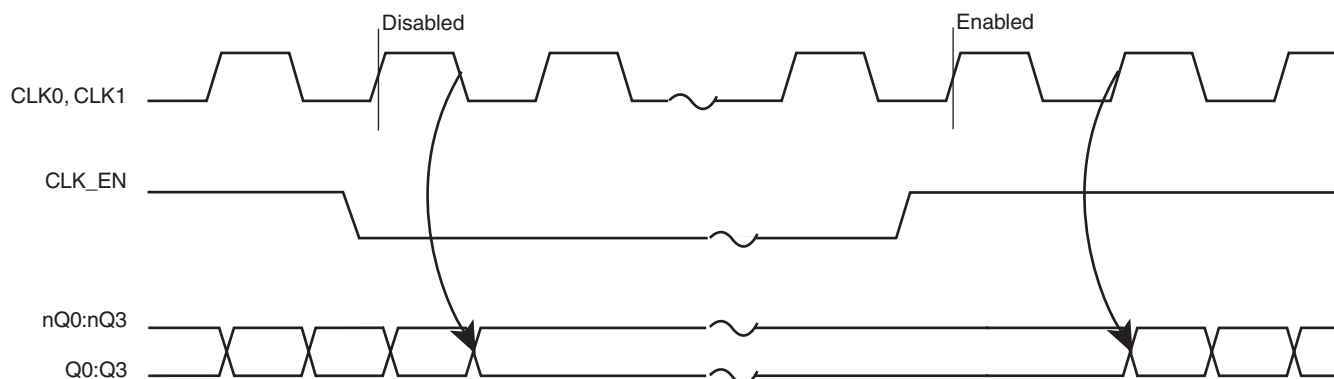


FIGURE 1. CLK_EN TIMING DIAGRAM

TABLE 3B. CLOCK INPUT FUNCTION TABLE

Inputs	Outputs	
CLK0 or CLK1	Q0:Q3	nQ0:nQ3
0	LOW	HIGH
1	HIGH	LOW



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ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V_{CC}	4.6V
Inputs, V_I	-0.5V to $V_{CC} + 0.5V$
Outputs, I_O	
Continuous Current	50mA
Surge Current	100mA
Package Thermal Impedance, θ_{JA}	
20 Lead TSSOP	73.2°C/W (0 lfpm)
20 Lead VFQFN	38.5°C/W (0 mps)
Storage Temperature, T_{STG}	-65°C to 150°C

NOTE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

TABLE 4A. POWER SUPPLY DC CHARACTERISTICS, $V_{CC} = 3.3V \pm 5\%$, $T_A = -40^\circ C$ TO $85^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{CC}	Positive Supply Voltage		3.135	3.3	3.465	V
I_{EE}	Power Supply Current			45		mA

TABLE 4B. LVC MOS / LVTTL DC CHARACTERISTICS, $V_{CC} = 3.3V \pm 5\%$, $T_A = -40^\circ C$ TO $85^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{IH}	Input High Voltage	CLK0, CLK1	2		$V_{CC} + 0.3$	V
		CLK_EN, CLK_SEL	2		$V_{CC} + 0.3$	V
V_{IL}	Input Low Voltage	CLK0, CLK1	-0.3		1.3	V
		CLK_EN, CLK_SEL	-0.3		0.8	V
I_{IH}	Input High Current	CLK0, CLK1, CLK_SEL	$V_{IN} = V_{CC} = 3.465V$		150	μA
		CLK_EN	$V_{IN} = V_{CC} = 3.465V$		5	μA
I_{IL}	Input Low Current	CLK0, CLK1, CLK_SEL	$V_{IN} = 0V, V_{CC} = 3.465V$	-5		μA
		CLK_EN	$V_{IN} = 0V, V_{CC} = 3.465V$	-150		μA

TABLE 4C. LVPECL DC CHARACTERISTICS, $V_{CC} = 3.3V \pm 5\%$, $T_A = -40^\circ C$ TO $85^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
V_{OH}	Output High Voltage; NOTE 1		$V_{CC} - 1.4$		$V_{CC} - 0.9$	V
V_{OL}	Output Low Voltage; NOTE 1		$V_{CC} - 2.0$		$V_{CC} - 1.7$	V
V_{SWING}	Peak-to-Peak Output Voltage Swing		0.6		1.0	V

NOTE 1: Outputs terminated with 50Ω to $V_{CC} - 2V$.



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TABLE 5. AC CHARACTERISTICS, $V_{CC} = 3.3V \pm 5\%$, $T_A = -40^\circ C$ TO $85^\circ C$

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
f_{MAX}	Output Frequency				266	MHz
t_{PD}	Propagation Delay; NOTE 1			1.3		ns
$tsk(o)$	Output Skew; NOTE 2, 4			TBD		ps
$tsk(pp)$	Part-to-Part Skew; NOTE 3, 4			TBD		ps
f_{jit}	Buffer Additive Phase Jitter, RMS; refer to Additive Phase Jitter section	$f = 155.52MHz$ (Integration Range: 12KHz - 20MHz)		0.04		ps
t_R / t_F	Output Rise/Fall Time	20% to 80% @ 50MHz		450		ps
odc	Output Duty Cycle			50		%

All parameters measured at 266MHz unless noted otherwise.

The cycle-to-cycle jitter on the input will equal the jitter on the output. The part does not add jitter.

NOTE 1: Measured from the $V_{CC}/2$ of the input to the differential output crossing point.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.

Measured at the output differential cross points.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.



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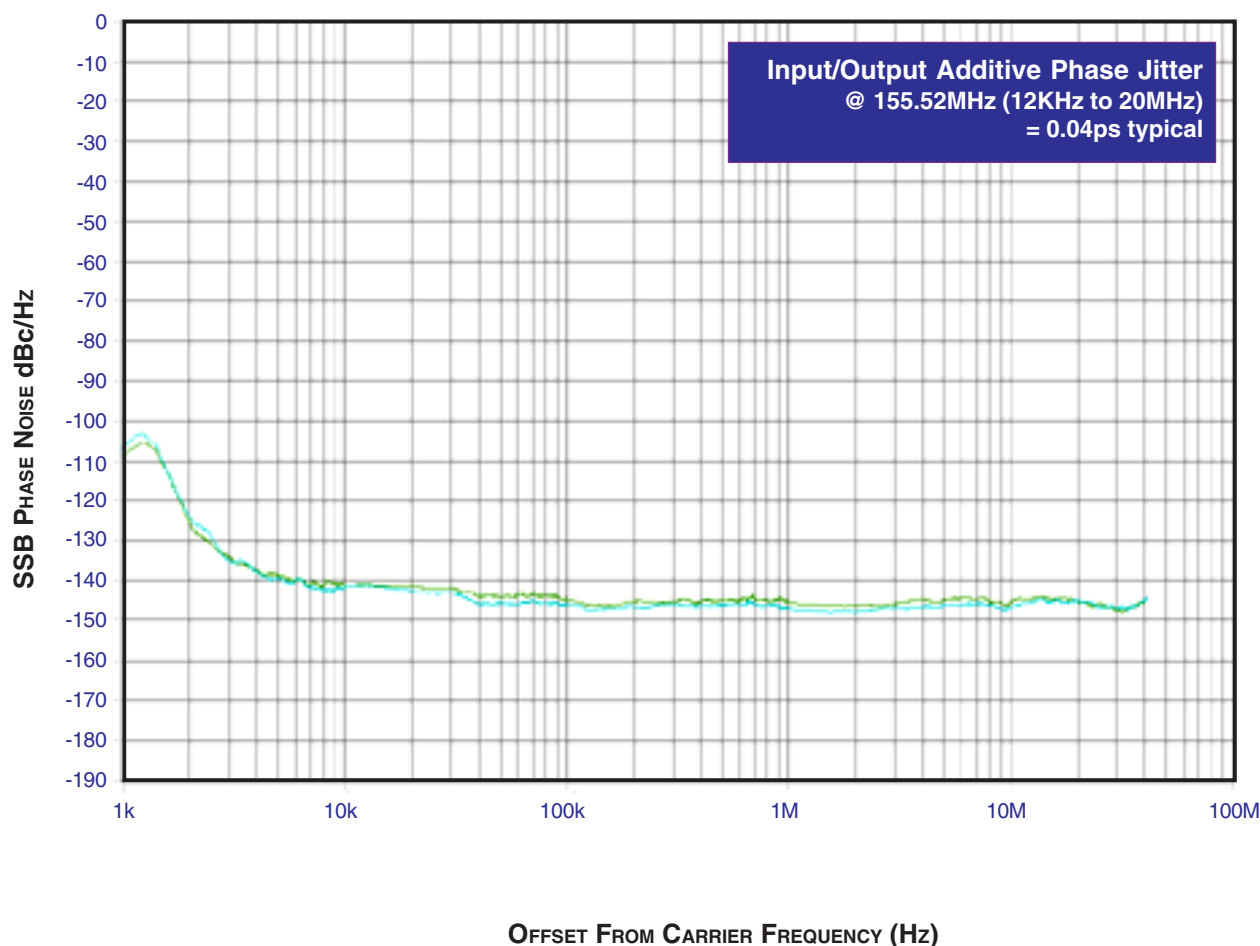
LOW SKEW, 1-TO-4

LVC MOS/LVTTL-TO-3.3V LVPECL FANOUT BUFFER

ADDITIVE PHASE JITTER

The spectral purity in a band at a specific offset from the fundamental compared to the power of the fundamental is called the ***dBc Phase Noise***. This value is normally expressed using a Phase noise plot and is most often the specified plot in many applications. Phase noise is defined as the ratio of the noise power present in a 1Hz band at a specified offset from the fundamental frequency to the power value of the fundamental. This ratio is expressed in decibels (dBm) or a ratio of the power

in the 1Hz band to the power in the fundamental. When the required offset is specified, the phase noise is called a ***dBc*** value, which simply means dBm at a specified offset from the fundamental. By investigating jitter in the frequency domain, we get a better understanding of its effects on the desired application over the entire time record of the signal. It is mathematically possible to calculate an expected bit error rate given a phase noise plot.



As with most timing specifications, phase noise measurements have issues. The primary issue relates to the limitations of the equipment. Often the noise floor of the equipment is higher than the noise floor of the device. This is illustrated above. The

device meets the noise floor of what is shown, but can actually be lower. The phase noise is dependant on the input source and measurement equipment.



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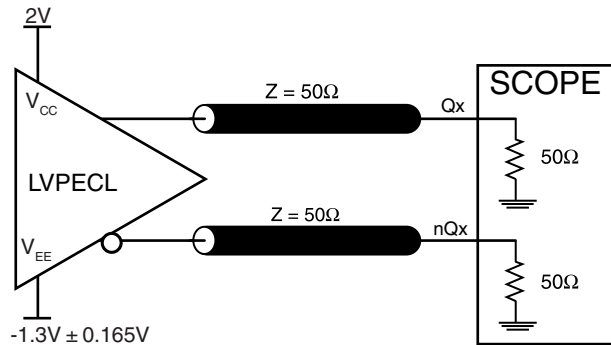
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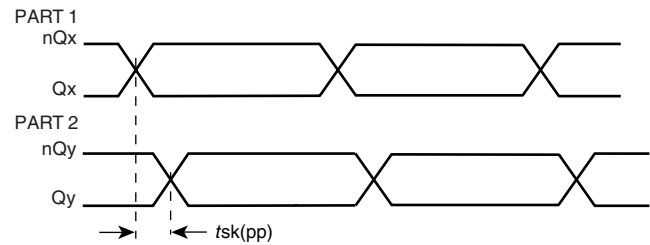
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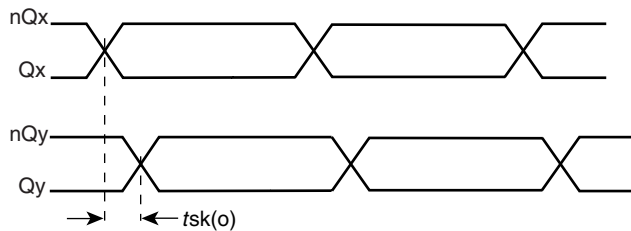
PARAMETER MEASUREMENT INFORMATION



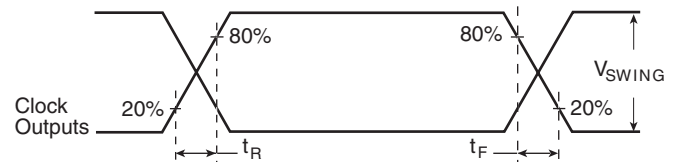
3.3V OUTPUT LOAD AC TEST CIRCUIT



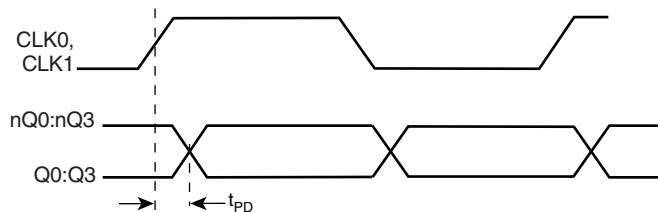
PART-TO-PART SKEW



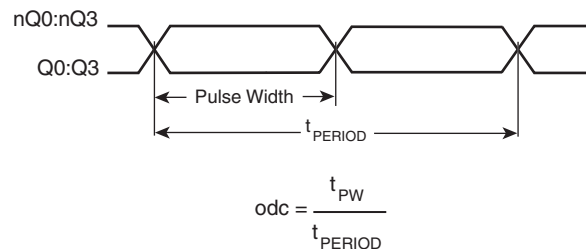
OUTPUT SKEW



OUTPUT RISE/FALL TIME



PROPAGATION DELAY



OUTPUT DUTY CYCLE/ PULSE WIDTH/PERIOD



APPLICATION INFORMATION

TERMINATION FOR LVPECL OUTPUTS

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUT and nFOUT are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to

drive 50Ω transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. *Figures 2A and 2B* show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.

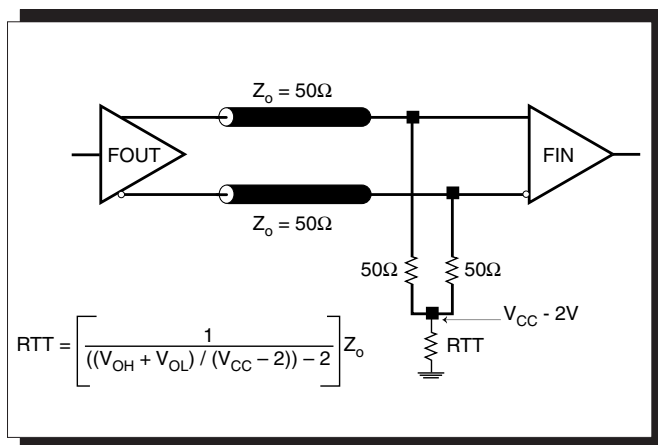


FIGURE 2A. LVPECL OUTPUT TERMINATION

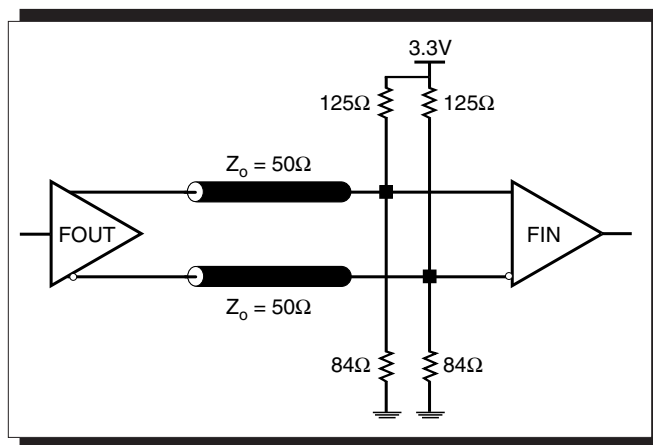


FIGURE 2B. LVPECL OUTPUT TERMINATION



POWER CONSIDERATIONS

This section provides information on power dissipation and junction temperature for the ICS8535BI-01. Equations and example calculations are also provided.

1. Power Dissipation.

The total power dissipation for the ICS8535BI-01 is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for $V_{CC} = 3.3V + 5\% = 3.465V$, which gives worst case results.

NOTE: Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)_{MAX} = $V_{CC_MAX} * I_{EE_MAX} = 3.465V * 45mA = 155.9mW$
- Power (outputs)_{MAX} = **30mW/Loaded Output pair**
If all outputs are loaded, the total power is $4 * 30mW = 120mW$

$$\text{Total Power}_{MAX} (3.465V, \text{ with all outputs switching}) = 155.9mW + 120mW = 275.9mW$$

2. Junction Temperature.

Junction temperature, T_j , is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS™ devices is 125°C.

The equation for T_j is as follows: $T_j = \theta_{JA} * Pd_total + T_A$

T_j = Junction Temperature

θ_{JA} = Junction-to-Ambient Thermal Resistance

Pd_total = Total Device Power Dissipation (example calculation is in section 1 above)

T_A = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance θ_{JA} must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 66.6°C/W per Table 6A below.

Therefore, T_j for an ambient temperature of 70°C with all outputs switching is:

$$70^\circ C + 0.276W * 66.6^\circ C/W = 88.38^\circ C. \text{ This is well below the limit of } 125^\circ C.$$

This calculation is only an example. T_j will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

TABLE 6A. THERMAL RESISTANCE θ_{JA} FOR 20-PIN TSSOP, FORCED CONVECTION

θ_{JA} by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	114.5°C/W	98.0°C/W	88.0°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	73.2°C/W	66.6°C/W	63.5°C/W
NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.			

TABLE 6B. θ_{JA} VS. AIR FLOW TABLE FOR 20 LEAD VFQFN

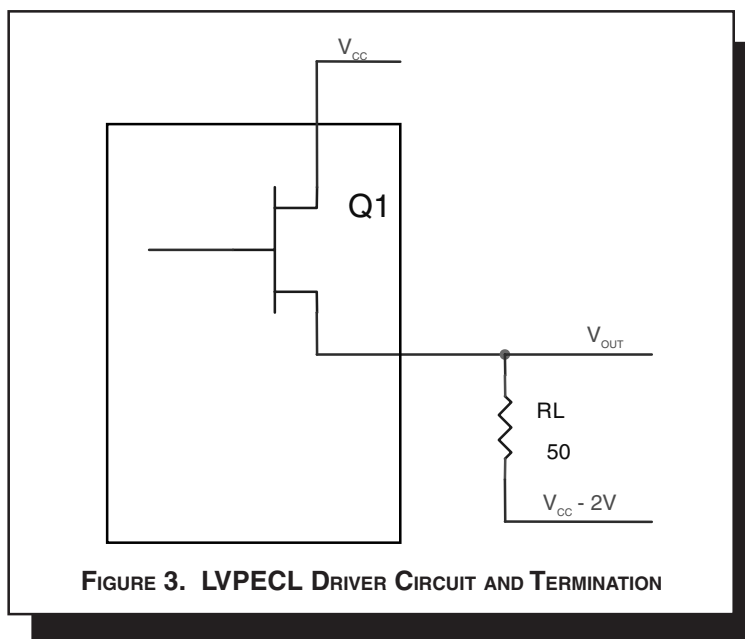
θ_{JA} by Velocity (Meters Per Second)			
	0	1	2.5
Single-Layer PCB, JEDEC Standard Test Boards	141.7°C/W	126.0°C/W	116.9°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	38.5°C/W	35.0°C/W	33.4°C/W
NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.			



3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVPECL output driver circuit and termination are shown in *Figure 3*.



To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of $V_{CC} - 2V$.

- For logic high, $V_{OUT} = V_{OH_MAX} = V_{CC_MAX} - 0.9V$

$$(V_{CC_MAX} - V_{OH_MAX}) = 0.9V$$

- For logic low, $V_{OUT} = V_{OL_MAX} = V_{CC_MAX} - 1.7V$

$$(V_{CC_MAX} - V_{OL_MAX}) = 1.7V$$

Pd_H is power dissipation when the output drives high.

Pd_L is the power dissipation when the output drives low.

$$Pd_H = [(V_{OH_MAX} - (V_{CC_MAX} - 2V))/R_L] * (V_{CC_MAX} - V_{OH_MAX}) = [(2V - (V_{CC_MAX} - V_{OH_MAX}))/R_L] * (V_{CC_MAX} - V_{OH_MAX}) = [(2V - 0.9V)/50\Omega] * 0.9V = 19.8mW$$

$$Pd_L = [(V_{OL_MAX} - (V_{CC_MAX} - 2V))/R_L] * (V_{CC_MAX} - V_{OL_MAX}) = [(2V - (V_{CC_MAX} - V_{OL_MAX}))/R_L] * (V_{CC_MAX} - V_{OL_MAX}) = [(2V - 1.7V)/50\Omega] * 1.7V = 10.2mW$$

Total Power Dissipation per output pair = $Pd_H + Pd_L = 30mW$



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RELIABILITY INFORMATION

TABLE 7A. θ_{JA} VS. AIR FLOW TABLE FOR 20 LEAD TSSOP

θ_{JA} by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	114.5°C/W	98.0°C/W	88.0°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	73.2°C/W	66.6°C/W	63.5°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

TABLE 7B. θ_{JA} VS. AIR FLOW TABLE FOR 20 LEAD VFQFN

θ_{JA} by Velocity (Meters Per Second)			
	0	1	2.5
Single-Layer PCB, JEDEC Standard Test Boards	141.7°C/W	126.0°C/W	116.9°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	38.5°C/W	35.0°C/W	33.4°C/W

NOTE: Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.

TRANSISTOR COUNT

The transistor count for ICS8535BI-01 is: 412



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PACKAGE OUTLINE - G SUFFIX FOR 20 LEAD TSSOP

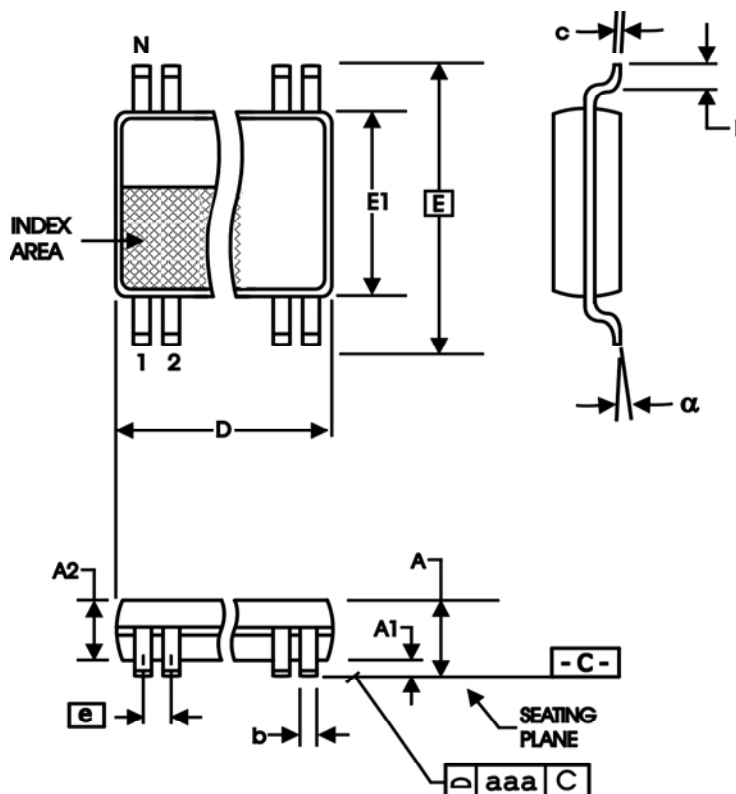


TABLE 8A. PACKAGE DIMENSIONS

SYMBOL	Millimeters	
	Minimum	Maximum
N	20	
A	--	1.20
A1	0.05	0.15
A2	0.80	1.05
b	0.19	0.30
c	0.09	0.20
D	6.40	6.60
E	6.40 BASIC	
E1	4.30	4.50
e	0.65 BASIC	
L	0.45	0.75
α	0°	8°
aaa	--	0.10

REFERENCE DOCUMENT: JEDEC PUBLICATION 95, MO-153



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PACKAGE OUTLINE - K SUFFIX FOR 20 LEAD VFQFN

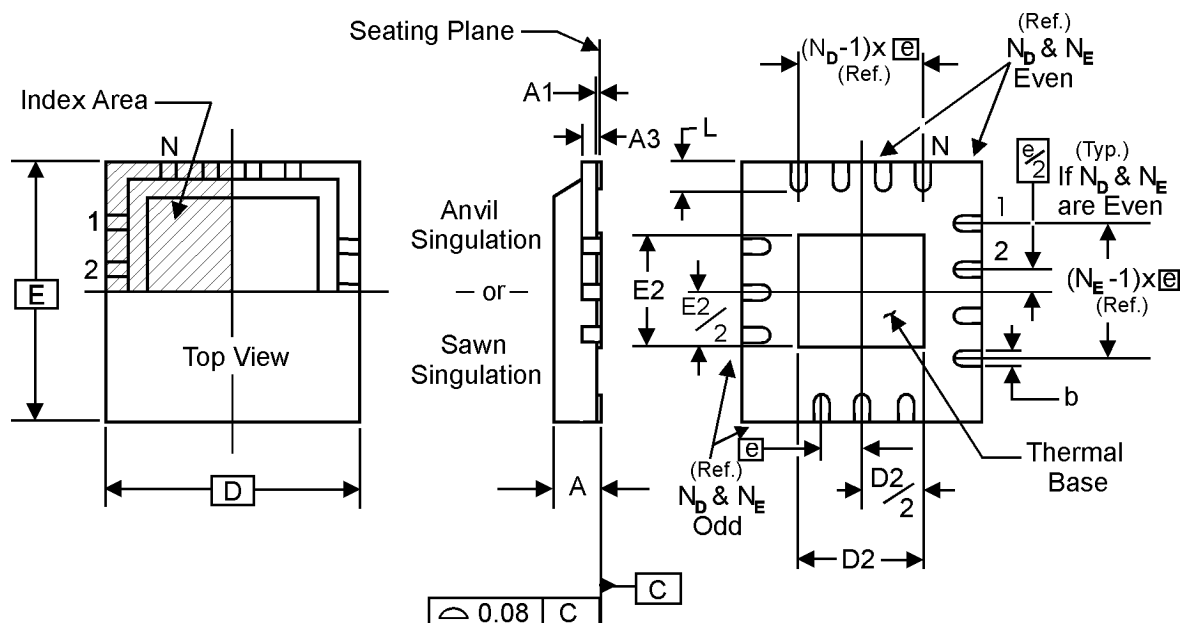


TABLE 8B. PACKAGE DIMENSIONS

JEDEC VARIATION ALL DIMENSIONS IN MILLIMETERS		
SYMBOL	MINIMUM	MAXIMUM
N	20	
A	0.80	1.0
A1	0	0.05
A3	0.25 Reference	
b	0.18	0.30
e	0.50 BASIC	
N _D	5	
N _E	5	
D	4.0	
D2	0.75	2.80
E	4.0	
E2	0.75	2.80
L	0.35	0.75

Reference Document: JEDEC Publication 95, MO-220



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TABLE 9. ORDERING INFORMATION

Part/Order Number	Marking	Package	Shipping Packaging	Temperature
ICS8535BGI-01	TBD	20 Lead TSSOP	tube	-40°C to 85°C
ICS8535BGI-01T	TBD	20 Lead TSSOP	2500 tape & reel	-40°C to 85°C
ICS8535BGI-01LF	TBD	20 Lead "Lead Free" TSSOP	tube	-40°C to 85°C
ICS8535BGI-01LFT	TBD	20 Lead "Lead Free" TSSOP	2500 tape & reel	-40°C to 85°C
ICS8535BKI-01	TBD	20 Lead VFQFN	tube	-40°C to 85°C
ICS8535BKI-01T	TBD	20 Lead VFQFN	490 tape & reel	-40°C to 85°C

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